AEROSPACE DATA EXCHANGE PROGRAM TRANSMITTAL

PRODUCT INFORMATION NOTICE

1. TITLE MICROCIRCUIT, MEMORY, DIGITAL,CMOS, FOUR-2MG X 8-BIT OR ONE – 8MEG X 8BIT (64M), USER-CONFIGURABLE, PADIATION-HARDENED, MAGNETORESISTIVE RAM (MRAM), MULTICHIP MODULE (MCM)	**2. DOCUMENT NUMBER** SPO-2019-PIN-0001
	3. DATE ***(Year, Month, Date)*** 2019, JUNE, 26
4. MANUFACTURER NAME AND ADDRESS CAES 4350 CENTENNIAL BOULEVARD COLORADO SPRINGS, COLORADO 80907-3486	**5. MANUFACTURER POINT OF CONTACT NAME** Mike Leslie
	6. MANUFACTURER POINT OF CONTACT TELEPHONE 710 594-8000
	7. MANUFACTURER POINT OF CONTACT EMAIL mike.leslie@caes.com

8. CAGE CODE 65342	**9. BLANK**	**10. PRODUCT IDENTIFICATION CODE** MQ09	**11. BASE PART** UT8MR8M8
12. BLANK		**13. SMD NUMBER** 5962-13207	**14. DEVICE TYPE DESIGNATOR** SEE DESCRIPTION
		15. RHA LEVELS H	**16. QML LEVEL** Q, Q+, V
		17. NON QML LEVEL Proto, HiRel	**18. GIDEP NUMBER** **GB4-I-19-0002**

19. DESCRIPTION (FOR NEW PRODUCTS, PROVIDE AVAILABILITY DATE AND LEAD TIME)

COBHAM SEMICONDUCTOR AND SPACE SOLUTIONS IS ISSUING A DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE FOR DEVICE TYPE 01 AND 02 OF THIS SMD. THIS PIN ADDS NEW DEVICES TPE 03 AND 04 AND DESCRIBES THE CHANGES TO THE SMD DUE TO PROCESS AND QUALIFICATION FLOW CHANGES. THIS PIN ALSO PROVIDES NOTIFICATION AND CORRECTION OF A REQUIRMENT CONTAINED IN THE SMD:

*****SPECIFICATION CHANGE NOTED FOR PARAGRAPH 4.2.1d (page 10)*****
DEVICE TYPE 02 WAS PREVIOUSLY NOTED (6) AS 5% PDA FOR DC AND FUCNTIONAL TEST COMBINED. DEVICE TYPE 02 WAS PROCESSED AS 10% PDA FOR DC AND FUNCTIONAL TEST COMBINED. THIS WAS AN ERROR IN THE SMD AS COBHAM TYPICALLY REQUIRES A 10% PDA FOR MULTICHIP MODULE ASSEMBLIES.

ADDS DEVICE TYPES 03 AND 04 TO SECTION 1.2.2 (PAGE 2)

Device type	Generic number	Circuit function	Access time
03	UT8MR8M8	8M X 8-bit rad-hard MRAM 2/	50ns
04	UT8MR8M8	8M X 8-bit rad-hard MRAM 1/ 2/	50ns

DEVICE TYPE 04 ADDED TO NOTE 1/ ON PAGE 2.

DEVICE TYPE 03 AND 04 ADDS NOTE 2/ TO SMD PAGE 2.
2/ DEVICE TYPE 03 AND 04 INCLUDE COLD WAFER PROBE (-40C) AS PART OF THE PRODUCTION FLOW.

ADD DEVICE TYPE 04 TO 4.2.1d
Additional screening for device types 02 and 04.

Continued on page 2:

NOTE: THIS DOCUMENT IS PUBLISHED FOR INFORMATION PURPOSES AND MAY PROVIDE FORWARD LOOKING STATEMENTS THAT ARE SUBJECT TO CHANGE. THE USERS SHOULD CONTACT THEIR LOCAL CAES SALES OFFICE FOR ANY ACTIONABLE CONTENT DESCRIBED HEREIN.

CHANGE NOTE (6) OF 4.2.1d (page 10):

(6) Dynamic burn-in at +125ºC for 240 hours or equivalent and static burn-in at +125C for 144 hours (device type 04 only method 1015 of MIL-STD-883), deltas, PDA (3%) for Functional Test only, and PDA (10%) for DC and Functional Test combined.

ADD DEVICE TYPE 04 TO NOTE 6/ OF TABLE IIA (page 24)

ADD NOTE 3/ TO STANDARD MICROCIRCUIT DRAWING BULLETIN PAGE AND REPLACE VENDOR CAGE NUMBER FOR ALL DEVICE TYPES 01 AND 02 WITH NOE 3/

3/ NOT AVAILABLE FROM AND APPROVED SOURCE OF SUPPLY

ADD DEVICE TYPE 03 AND 04 TO 5962-13207 SMD BULLETIN PAGE AS BELOW:

5962H1320703QXC	65342	UT8MR8M8-50XQC
5962H1320704QXC	65342	UT8MR8M8-50XQC